Express Mail No. ER534274197US Attorney Docket No.: AM-5852.D1



IN RE APPLICATION OF: Scott Fuller et al.

SERIAL NO.: 10/758,827

FILED: January 15, 2004

FOR: METHOD OF INCREASING THE SHELF LIFE

OF A PHOTOMASK SUBSTRATE

§ GROUP ART UNIT: 1756

(Parent Application)

EXAMINER: N. M. Barreca

(Parent Application

8

§ Attorney Docket No.:

AM-5852.D1

Date: February 18, 2004

# INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR § 1.97(b)(1)

Hon. Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

In accordance with 37 CFR § 1.97(b)(1), applicants hereby request consideration of this Information Disclosure Statement. This Information Disclosure Statement is being submitted within three (3) months of the filing date of the subject application. Applicants are providing herewith a copy of each document cited on the attached Form PTO-1449.

## **CERTIFICATE OF MAILING UNDER 37 CFR § 1.10**

I hereby certify that this paper is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as U.S. EXPRESS MAIL NO. ER534274197US in an envelope addressed to: Mail Stop DD, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Date: February 18, 2004

Shirley L. Church, Reg. No. 31,858

The submission of this Information Disclosure Statement and Form PTO-1449 is not an admission that the art cited is "prior art" with respect to the present invention, nor is it a representation that no better art exists. Applicants hereby reserve the right to swear behind or otherwise disprove any alleged "prior" nature of any art cited should the facts support and the situation warrant such an action.

If the Examiner has any questions, she is respectfully requested to contact the undersigned attorney at the telephone number set forth below.

Respectfully submitted,

Shirley L. Church

Registration No. 31,858 Attorney for Applicants

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Applied Materials, Inc.
P.O. Box 450-A
Santa Clara, California 95052



Express Mail No. ER534274197US Attorney Docket No.: AM-5852.D1

E UNITED STATES PATENT AND TRADEMARK OFFICE

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## **INFORMATION DISCLOSURE STATEMENT** TRANSMITTAL LETTER

Hon. Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Applicants are submitting the subject Information Disclosure Statement under 37 CFR § 1.97(b)(1). This Information Disclosure Statement is being submitted within three (3) months of the filing date of the subject application.

# **CERTIFICATE OF MAILING UNDER 37 CFR § 1.10**

I hereby certify that this paper is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as U.S. EXPRESS MAIL NO. ER534274197US in an envelope addressed to: Mail Stop DD, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: February 18, 2004

Shirley L. Church, Reg. No. 31,858

Applicants do not believe that any fee is due in connection with the filing of this Information Disclosure Statement under 37 CFR § 1.97(b)(1). However, in the event that any additional fee is due, the Commissioner is hereby authorized to charge Deposit Account No. <u>50-1512</u> of Shirley L. Church, Sunnyvale, California, in the amount of such fee.

This transmittal letter is submitted in duplicate for accounting purposes.

Respectfully submitted,

Shirley L. Church

Registration No. 31,858 Attorney for Applicants

Correspondence Address:
Patent Counsel
Applied Materials, Inc.
P.O. Box 450-A
Santa Clara, California 95052

FORM PTO-1449 (Equivalent)

U.S. Department of Commerce Patent and Trademark Office U.S. Application Serial No. 10/758,827

Atty. Docket No. AM-5852.D1



INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

Scott Fuller et al. Applicants

January 15, 2004 Filing Date

<u>1756</u> Group

#### **U. S. PATENT DOCUMENTS**

Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date  If Appropriate
	4,102,683	07/25/78	DiPiazza	96	38.4	
	4,357,416	11/02/82	Fan	430	302	
	5,234,990	08/10/93	Flaim et al. *	524	609	
	5,278,010	01/11/94	Day et al.	430	18	
	5,554,485	09/10/96	Dichiara et al. *	430	271.1	
	5,723,237	03/03/98	Kobayashi et al. *	430	30	
<del></del>	5,879,853	03/09/99	Azuma *	430	166	
	5,879,863	03/09/99	Azuma et al.	430	322	
	5,935,768	08/10/99	Biche et al. **	430	401	
	5,939,236	08/17/99	Pavelchek et al.	430	273.1	
	6,048,672	04/11/00	Cameron et al.	430	327	
· ·	6,110,638	08/29/00	Masuda et al. **	430	270.1	
			1			

Examiner Date Considered

Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>\*</sup> Cited in a Search Report in corresponding PCT Application No. PCT/US02/22609.

<sup>\*\*</sup> Cited during the prosecution of the parent application, U.S. Application Serial No. 09/912,116.

U. S. PATENT DOCUMENT	
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Examiner <u>Initial</u>	Document Number	Issue <u>Date</u>	Name	Class	Subclass	Filing Date If Appropriate
	6,156,479	12/05/00	Meador et al.	430	270.1	
	6,169,029	01/02/01	Yang **	438	671	
	6,183,915	02/06/01	Rolfson **	· 430	5	
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	6,340,553	01/22/02	Oomori et al. **	430	270.1	06/02/00
	6,353,209	03/05/02	Schaper et al. **	219	444.1	12/08/99
	6,433,348	08/13/02	Abboud et al. **	250	492.2	07/25/00

### **U. S. PATENT APPLICATION DOCUMENTS**

Examiner Initial	Document Number	Publication Date	<u>Name</u>	Class	Subclass	Filing Date
	2002/0012876 A1	01/31/02	Angelopolous et al. *	430	271.1	08/17/01
	2002/0182514 A1	12/05/02	Montgomery et al. **	430	5	05/03/01

Examiner Date Considered

Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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<sup>\*\*</sup> Cited during the prosecution of the parent application, U.S. Application Serial No. 09/912,116.

#### FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Publication <u>Date</u>	n Name	Class	Subclass	Translation (If Appropriate)
	EP 0588087	03/23/94	Ogawa et al. *	H01L	21/027	
	EP 0905565	03/31/99	Lu et al. *	G03F	7/09	
	EP 0987600	03/22/00	Adams et al. *	G03F	7/09	
	EP 0989460	03/29/00	Shimomura et al.	G03F	7/004	
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	JP 10048831	02/20/98	Sony Corp.	G03F	007/11	Abstract
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	WO 0046643	08/10/00	Smith et al. *	G03F	9/00	
	WO 0054105	09/14/00	Foster et al.	G03C	1/492	

Examiner Date Considered

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Examiner  Examiner: I	Date Considered  nitial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in
<del></del>	M. Zuniga et al., "Application of a General Reaction/Diffusion Resist Model to Emerging Materials with Extension to Non-Actinic Exposure", <i>SPIE</i> , Vol. 3049, pp. 256-268 (1997).
<del></del>	* C. P. Soo et al., "Enhancement or Reduction of Catalytic Dissolution Reaction in Chemically Amplified Resists by Substrate Contaminants", <i>IEEE Transactions on Semiconductor Manufacturing</i> , Vol. 12, No. 4, pp. 462-469 (Nov 1999).
<del></del>	U. Okoroanyanwu et al., "Impact of Optical Absorption on Process Control for Sub-0.15- $\mu$ m Device Patterning Using 193-nm Lithography", <i>SPIE</i> , Vol. 3998, pp.781-790 (2000).
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	* G. Amblard et al., "Diffusion Phenomenon and Loss of Adhesion in Chemically Amplified Negative Resists", <i>Microelectronic Engineering</i> , 17, pp. 275-278 (1992).
	OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

Cited in a Search Report in corresponding PCT Application No. PCT/US02/22609. Cited during the prosecution of the parent application, U.S. Application Serial No. 09/912,116.